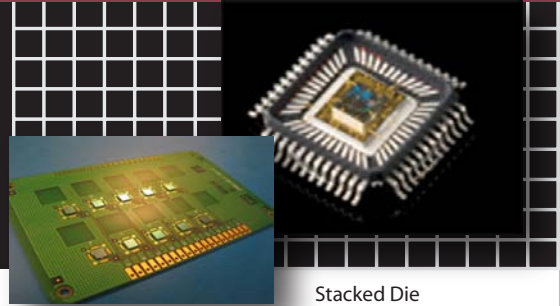


Flip Chip Packaging and Advanced Assembly Services



Flip Chip Technology

Stacked Die

Custom Solutions to Meet Your Quick-Turn Prototype Needs

Capabilities:

- Rapid prototyping of BGA, μ BGA, Area Array and CSP packaging
- Flip Chip assembly
- Chip-on-Board (COB) assembly
- Precision Die Attach
- Low Temperature Die Attach
- Ultra-Fine Pitch Wire Bonding
- Faster Time-to Market
- Flexibility to accommodate custom assembly projects

Quik-Pak specializes in advanced IC assembly and prototyping services for fabless semiconductor companies, enabling faster time to market for new devices. The unique assembly requirements for Flip Chip, Chip-on-Board, stacked die, Multi-Chip Modules, System-in-Package, BGA and MEMS devices are addressed by Quik-Pak's flexible processes and equipment, delivering prototypes to specification and on schedule.

Quik-Pak offers the following advanced IC package assembly options:

- Flip Chip assembly
- Complete laminate substrate services including design, fabrication, assembly, and BGA sphere attach
- Chip-on-Board (COB) and Chip-on-Flex assembly
- System-in-Package (SiP) and Multi-Chip Module (MCM) assembly
- MEMS packaging and assembly
- BGA packaging and assembly
- Wafer-Level Packaging (WLP)
- Stacked Die assembly
- Ultra-fine pitch wire bonding down to 35 μ m
- Complete wafer preparation services including wafer backgrinding, dicing, bumping, pick & place and inspection
- Die and wafer bumping
- Encapsulation options to JEDEC standard

Quik-Pak

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Quik-Pak is the ideal partner for advanced IC assembly and prototyping, whether you need a complete turnkey solution or individual services. Quik-Pak provides unparalleled flexibility, quality and outstanding customer service.